



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTN8962TA	Issued	14. May 2021
MA#	MA003664508		
Package	PG-TO263-7-1	Weight*	1534.51 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.162	0.08	0.08	757	757
chip_2	inorganic material	silicon	7440-21-3	3.697	0.24	0.24	2409	2409
chip_3	inorganic material	silicon	7440-21-3	1.212	0.08	0.08	790	790
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	iron	7439-89-6	0.810	0.05		528	
	non noble metal	copper	7440-50-8	808.613	52.69	52.76	526952	527638
wire	non noble metal	aluminium	7429-90-5	6.380	0.42	0.42	4158	4158
encapsulation	inorganic material	zinc oxide	1314-13-2	5.881	0.38		3832	
	miscellaneous	miscellaneous	-	23.523	1.53		15330	
	plastics	epoxy resin	-	88.213	5.75		57486	
	inorganic material	silicon dioxide	60676-86-0	470.467	30.66	38.32	306592	383240
lead finish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8496	8496
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	138	139
solder	non noble metal	tin	7440-31-5	0.091	0.01		59	
	noble metal	silver	7440-22-4	0.113	0.01		74	
	non noble metal	lead	7439-92-1	4.326	0.28	0.30	2819	2952
glue	plastics	Polyimide	26023-21-2	0.179	0.01	0.01	117	117
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
	non noble metal	copper	7440-50-8	106.210	6.92	6.93	69214	69304
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

- Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
- Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
- All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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